



TURBOSWITCH™ "A". ULTRA-FAST HIGH VOLTAGE DIODE

MAIN PRODUCT CHARACTERISTICS

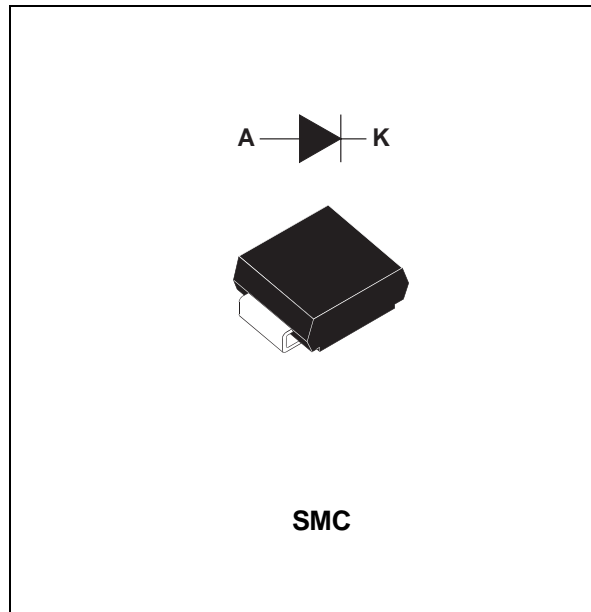
$I_{F(AV)}$	2A
V_{RRM}	1200V
t_{rr} (typ)	65ns
V_F (max)	1.5V

FEATURES AND BENEFITS

- SPECIFIC TO THE FOLLOWING OPERATIONS: SNUBBING OR CLAMPING, DEMAGNETIZATION AND RECTIFICATION
- ULTRA-FAST AND SOFT RECOVERY
- VERY LOW OVERALL POWER LOSSES IN BOTH THE DIODE AND THE COMPANION TRANSISTOR
- HIGH FREQUENCY OPERATION
- HIGH REVERSE VOLTAGE CAPABILITY
- SURFACE MOUNT DEVICE

DESCRIPTION

TURBOSWITCH 1200V drastically cuts losses in all high voltage operations which require extremely fast, soft and noise-free power diodes. Due to their optimized switching performances they also highly decrease power losses in any associated switching IGBT or MOSFET in all "Freewheel



Mode" operations and is particularly suitable and efficient in Motor Control circuitries, or in primary of SMPS as snubber, clamping or demagnetizing diodes, and also at the secondary of SMPS as high voltage rectifier diodes.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive peak reverse voltage	1200	V
V_{RSM}	Non repetitive peak reverse voltage	1200	V
$I_{F(RMS)}$	RMS forward current	8	A
I_{FRM}	Repetitive peak forward current	($t_p = 5 \mu s$ $f = 5kHz$) 50	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10ms$ sine 25	A
T_j	Maximum operating junction temperature	125	°C
T_{stg}	Storage temperature range	- 65 to + 150	°C

STTA212S

THERMAL AND POWER DATA

Symbol	Parameter	Conditions	Value	Unit
$R_{th(j-l)}$	Junction to lead thermal resistance		21	°C/W
P_1	Conduction power dissipation (see fig. 6)	$I_{F(AV)} = 1.5A$ $\delta = 0.5$ $T_{lead} = 72^\circ C$	2.5	W
P_{max}	Total power dissipation $P_{max} = P_1 + P_3$ ($P_3 = 10\% P_1$)	$T_{lead} = 67^\circ C$	2.8	W

STATIC ELECTRICAL CHARACTERISTICS (see Fig. 6)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_F *	Forward voltage drop	$I_F = 2A$ $T_j = 25^\circ C$ $T_j = 125^\circ C$		1.1	1.65 1.5	V
I_R **	Reverse leakage current	$V_R = 0.8$ $\times V_{RRM}$ $T_j = 25^\circ C$ $T_j = 125^\circ C$		150	20 400	μA
V_{to}	Threshold voltage	$T_j = 125^\circ C$			1.15	V
r_d	Dynamic resistance				175	m Ω

Test pulses widths : * $t_p = 380 \mu s$, $\delta < 2\%$

** $t_p = 5 ms$, $\delta < 2\%$

DYNAMIC ELECTRICAL CHARACTERISTICS

TURN-OFF SWITCHING (see Fig. 7)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
t_{rr}	Reverse recovery time	$T_j = 25^\circ C$ $I_F = 0.5 A$ $I_R = 1A$ $I_{rr} = 0.25A$ $I_F = 1 A$ $di_F/dt = -50A/\mu s$ $V_R = 30V$		65	115	ns
I_{RM}	Maximum recovery current	$T_j = 125^\circ C$ $V_R = 600V$ $I_F = 2A$ $di_F/dt = -16 A/\mu s$ $di_F/dt = -50 A/\mu s$		6.0	3.6	A
S factor	Softness factor	$T_j = 125^\circ C$ $V_R = 600V$ $I_F = 2A$ $di_F/dt = -50 A/\mu s$		0.9		/

TURN-ON SWITCHING (see Fig. 8)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
t_{fr}	Forward recovery time	$T_j = 25^\circ C$ $I_F = 2 A$ $di_F/dt = 16 A/\mu s$			900	ns
V_{Fp}	Peak forward voltage	measured at $1.1 \times V_{Fmax}$			35	V

APPLICATION DATA

The 1200V TURBOSWITCH has been designed to provide the lowest overall power losses in any all high frequency or high pulsed current operations.

In such applications (fig. 1 to 5), the way of calculating the power losses is given below :

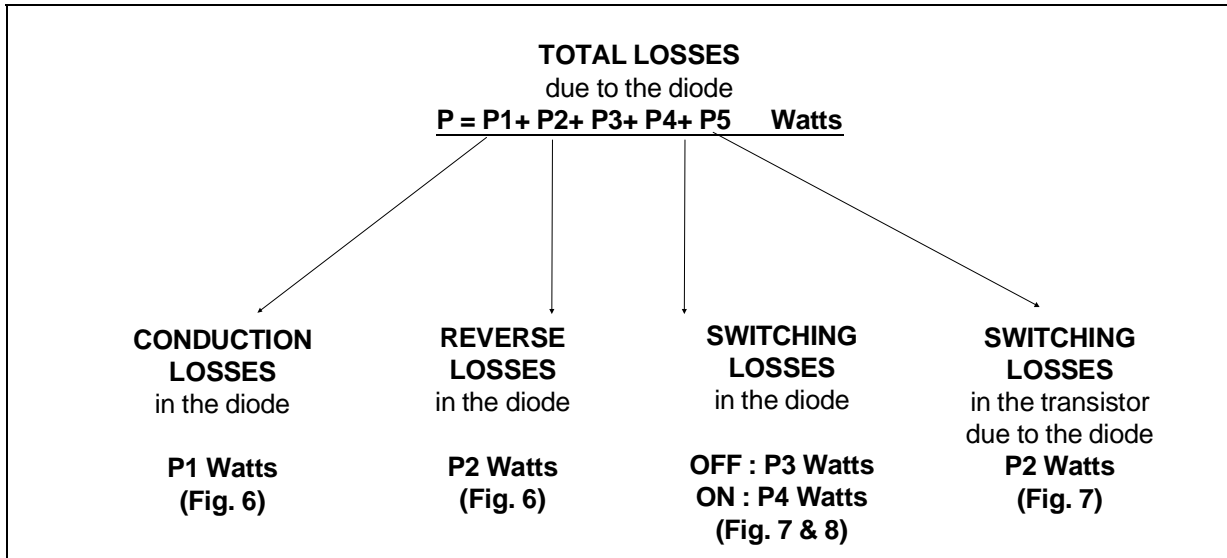
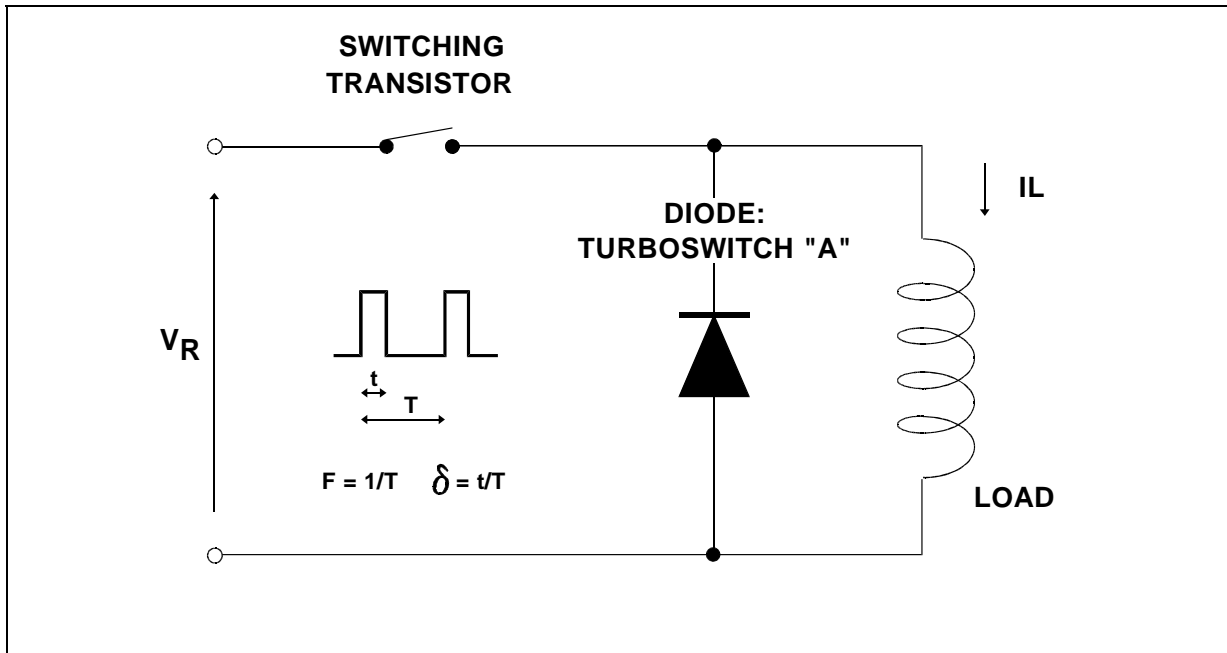


Fig. 1 : "FREEWHEEL" MODE



APPLICATION DATA (Cont'd)

Fig. 2 : SNUBBER DIODE.

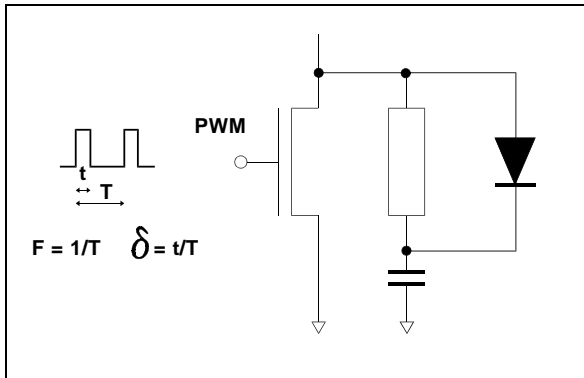


Fig. 3 : CLAMPING DIODE.

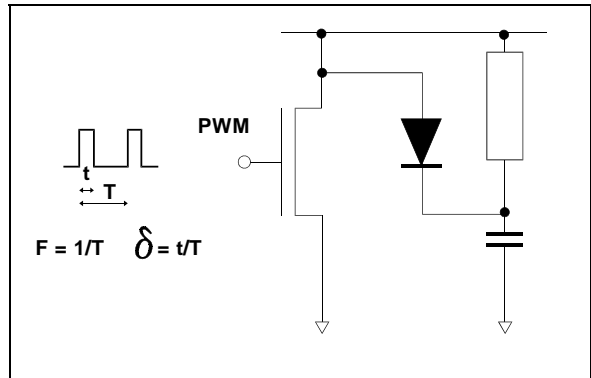


Fig. 4 : DEMAGNETIZING DIODE.

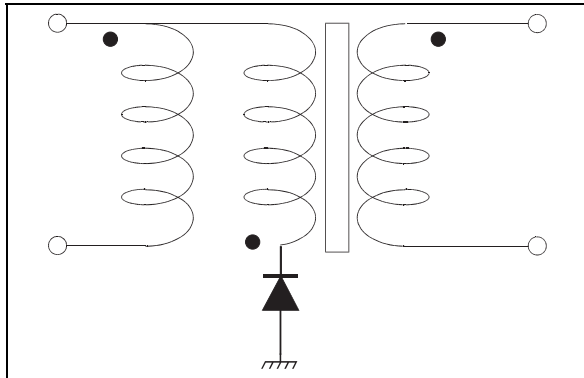


Fig. 5 : RECTIFIER DIODE.

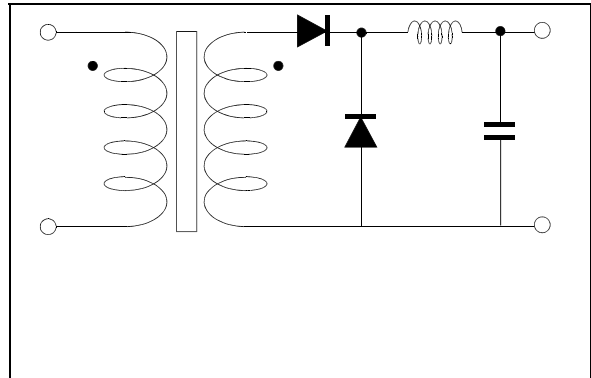
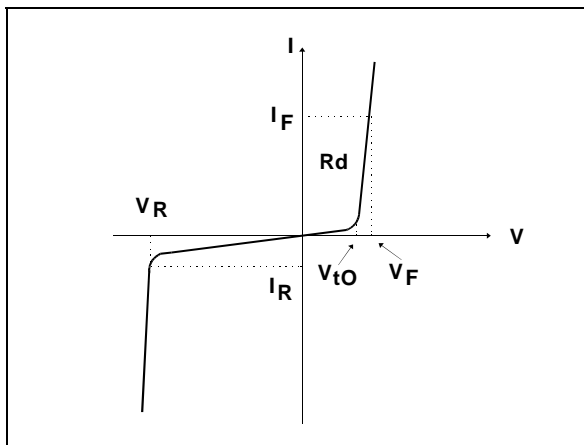


Fig. 6 : STATIC CHARACTERISTICS



Conduction losses :

$$P1 = V_{t0} \times I_F(AV) + R_d \times I_F^2(RMS)$$

Reverse losses :

$$P2 = V_R \times I_R \times (1 - \delta)$$

APPLICATION DATA (Cont'd)

Fig. 7 : TURN-OFF CHARACTERISTICS

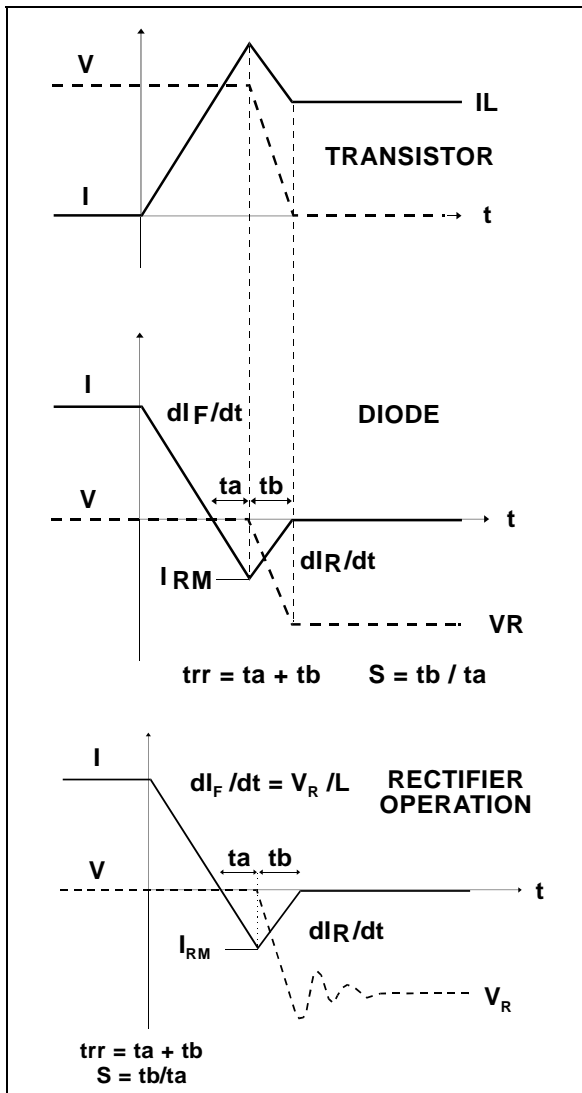
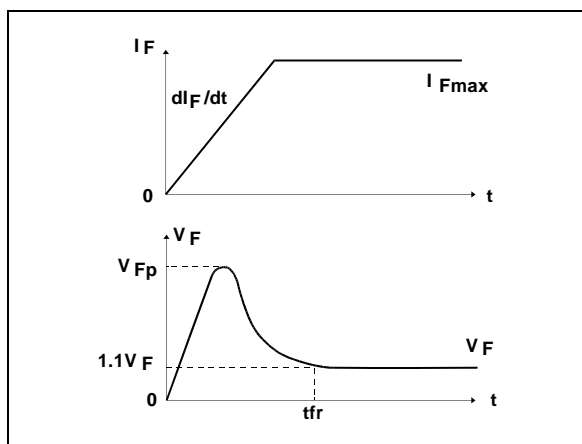


Fig. 8 : TURN-ON CHARACTERISTICS



Ratings and characteristics curves are ON GOING.

Turn-on losses :
(in the transistor, due to the diode)

$$P5 = \frac{V_R \times I_{RM}^2 \times (3 + 2 \times S) \times F}{6 \times dI_F/dt} + \frac{V_R \times I_{RM} \times I_L \times (S + 2) \times F}{2 \times dI_F/dt}$$

Turn-off losses (in the diode) :

$$P3 = \frac{V_R \times I_{RM}^2 \times S \times F}{6 \times dI_F/dt}$$

Turn-off losses :
with non negligible serial inductance

$$P3' = \frac{V_R \times I_{RM}^2 \times S \times F}{6 \times dI_F/dt} + \frac{L \times I_{RM}^2 \times F}{2}$$

P3, P3' and P5 are suitable for power MOSFET and IGBT

Turn-on losses :

$$P4 = 0.4 (V_{FP} - V_F) \times I_{Fmax} \times t_{fr} \times F$$

Fig. 9: Conduction losses versus average current.

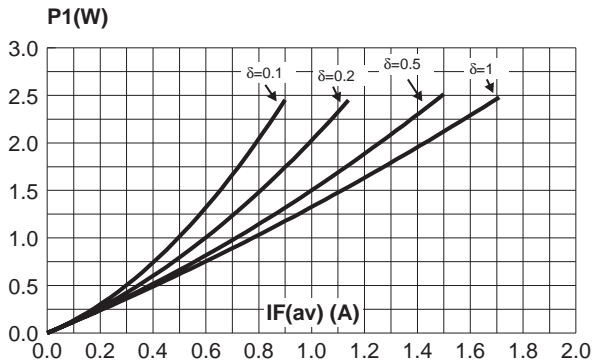


Fig. 11: Switching ON losses versus dIF/dt .

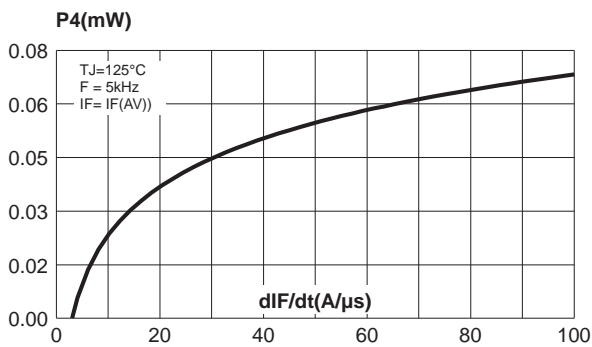


Fig. 13: Forward voltage drop versus forward current (maximum values).

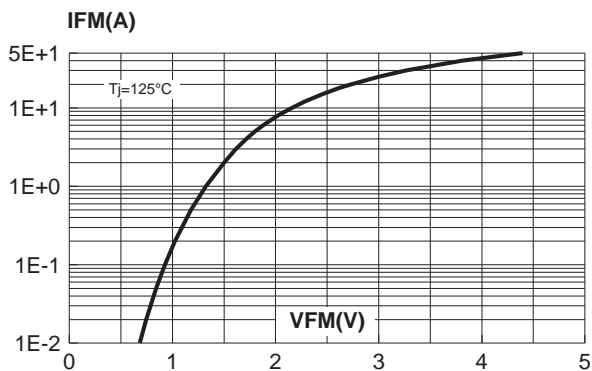


Fig. 10: Switching OFF losses versus dIF/dt .

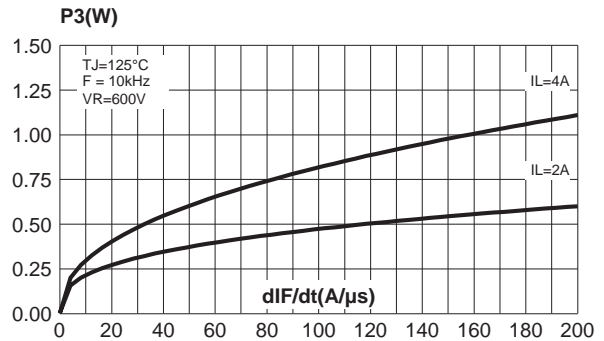


Fig. 12: Switching losses in transistor due to the diode.

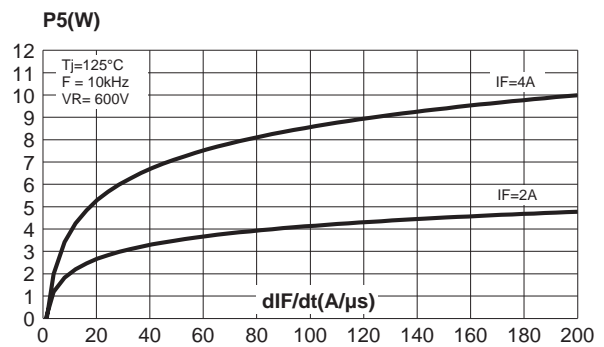


Fig. 14: Variation of thermal impedance junction to ambient versus pulse duration (epoxy printed circuit board FR4, $e(Cu)=35\mu m$, $S(Cu)=1cm^2$).

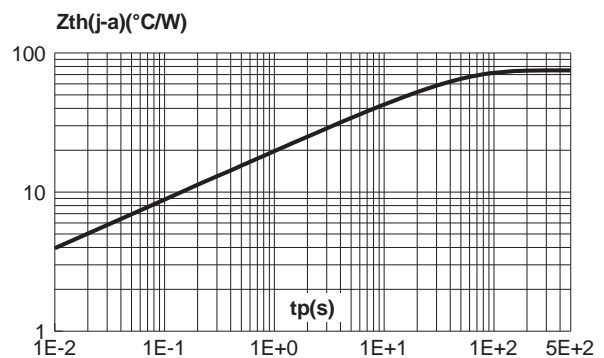


Fig. 15: Peak reverse recovery current versus di_F/dt (90% confidence).

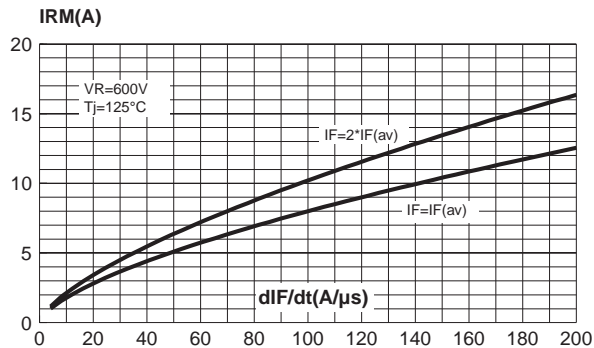


Fig. 17: Reverse recovery time versus di_F/dt (90% confidence).

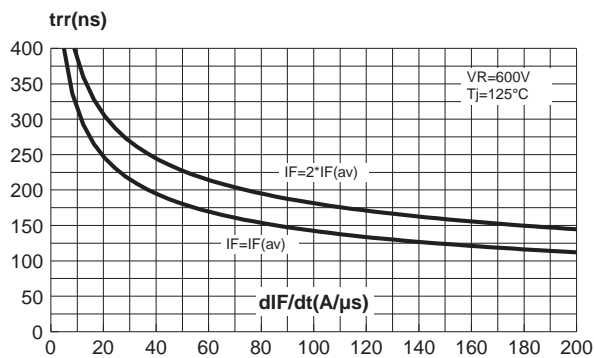


Fig. 19: Transient peak forward voltage versus di_F/dt .

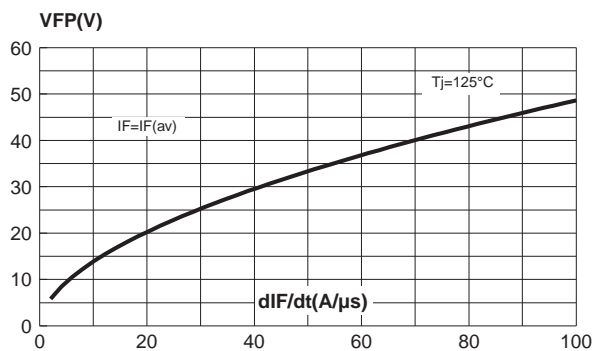


Fig. 16: Softness factor (t_b/t_a) versus di_F/dt (typical values).

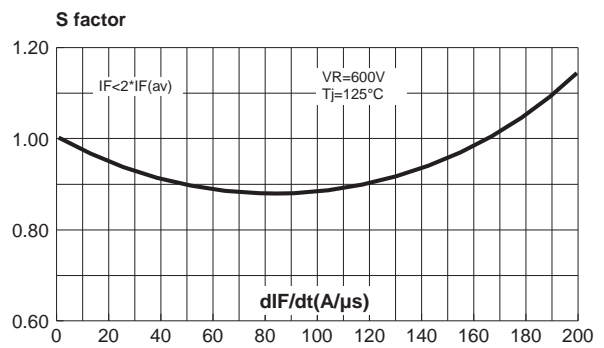


Fig. 18: Relative variation of dynamic parameters versus junction temperature (reference $T_j=125^\circ\text{C}$).

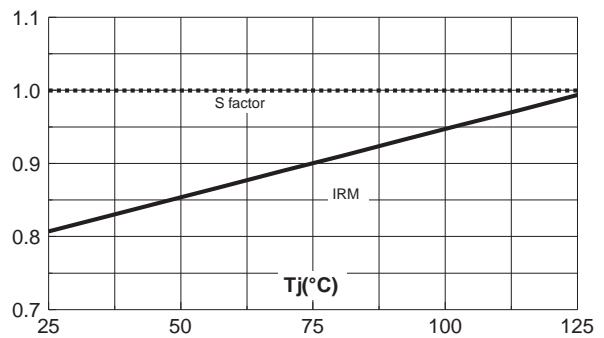
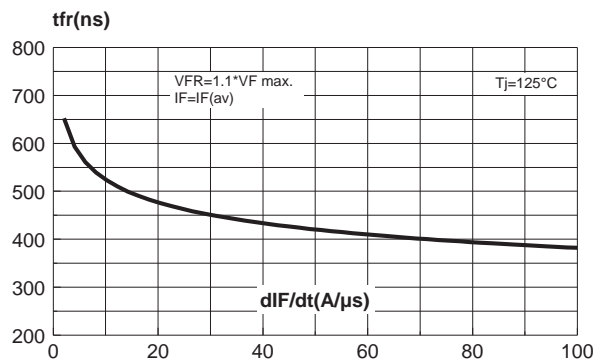
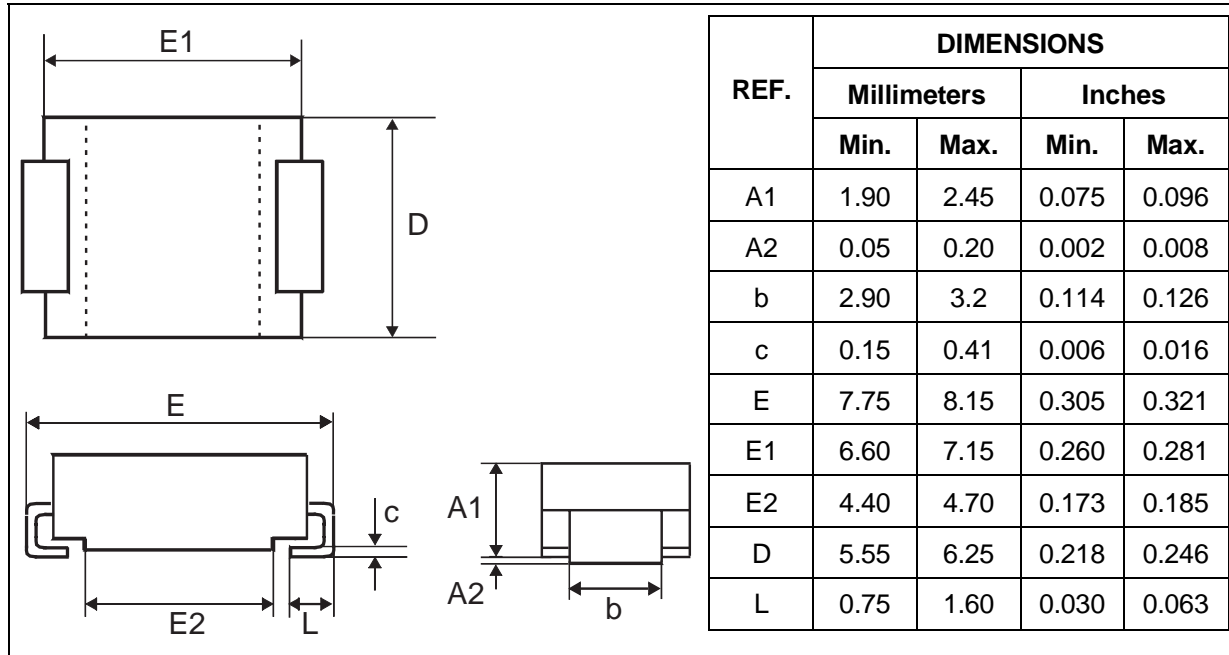


Fig. 20: Forward recovery time versus di_F/dt .

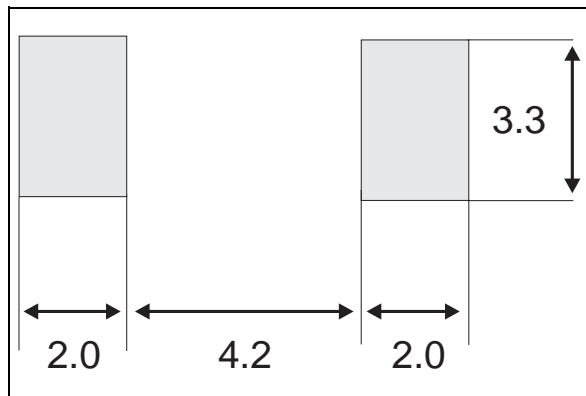


STTA212S

PACKAGE MECHANICAL DATA SMC



FOOTPRINT DIMENSIONS (in millimeters) SMC Plastic



Marking : T53
Laser marking
Band indicates cathode

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